

## **Device Material Content**

5555 NE Moore Ct. Assembly: ASEM Hillsboro OR 97124 Package Code: Size (mm): 17 x 17 custreg@latticesemi.com Package: 381 caBGA **BG381** Lead pitch (mm): 0.8 **Total Device Weight** 1.005 Grams **Products:** MSL: 3 FE5 Reflow max (°C): 260 June, 2022 % of Total % of Total Weight (g) Weight (g) % of Material Substance CAS# Notes / Assumptions: Pkg. Wt. Pkg. Wt. Die 2.65% 0.0266 Die size: 6.55 x 7.04 mm 2.65% 0.0266 7440-21-3 100.00% Silicon chip Mold Compound 0.4067 40.47% Mold Compound: Sumitomo G750SE (ULA) 2.83% 0.0285 7.00% Epoxy Resin 0.0203 Phenol Novolac 9003-35-4 2.02% 5.00% 0.0203 Metal Hydroxide 2.02% 5.00% 0.20% 0.0020 Carbon Black 1333-86-4 0.50% 33.39% 0.3355 Silica Fused 60676-86-0 82.50% D/A Epoxy 0.38% 0.0038 Die attach epoxy: Henkel (Ablebond) 2100A 0.30% 0.00306 Silver 7440-22-4 80.00% 0.08% 0.00076 20.00% Esters & resins Wire 0.26% 0.0026 0.8 mil diameter; 1 wire per solder ball 0.255% 0.00256 7440-50-8 98.50% Copper 0.004% 0.00004 Palladium 7440-05-3 1.50% Solder Balls 9.44% 0.0949 SAC305 9.11% 0.0916 7440-31-5 Tin (Sn) 96.50% 0.28% 0.0028 Silver (Ag) 7440-22-4 3.00% 0.05% 0.0005 7440-50-8 0.50% Copper (Cu) Substrate 27.61% 0.2775 BT Resin CCL-HL832NX-A 8.56% 0.0860 BT Resins 31.00% 18.77% 0.1887 Glass fiber 65997-17-3 68.00% Foil 12.56% 0.1262 10.30% 0.1035 7440-50-8 82.00% Copper 1.90% 0.0190 Nickel 7440-02-0 15.10% 0.37% 0.0037 Gold 7440-57-5 2.91% Solder Mask 6.63% 0.0666 Solder mask PSR4000 AUS 308 3.73% 0.0375 Quartz 14808-60-7 56.20% 1.06% 0.0107 3-methoxy-3-methylbutylacetate 103429-90-9 16.00% 1.46% 0.0147 Barium Sulfate 7727-43-7 22.00% 0.20% 0.0020 Talc (containing no asbestiform fibers) 14807-96-6 3.00% 0.19% 0.0019 Trade secret ingredients 2.80%

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